

Amendments to the Claims: This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1. (Original) An organic light-emitting device comprising:
 - a transparent substrate;
 - an anode layer;
 - a cathode layer;
 - organic functional layers sandwiched between the anode layer and the cathode layer;

and

an encapsulation layer fabricated on one side or both sides of the device;

wherein,

the encapsulation layer includes a thin multilayer structure which has a period number (n) of alternating layers formed of a polymer material layer and a ceramic material layer;

the encapsulation layer also includes a thick organic insulation layer on top of the thin multilayer structure, which is made up of polymer materials.

2. (Original) The organic light-emitting device of claim 1, wherein the substrate of the device includes one of glass and plastic.

3. (Original) The organic light-emitting device of claim 1, wherein the period number of the thin multilayer structure is an integer in the range of 1 to 10.

4. (Original) The organic light-emitting device of claim 1, wherein the polymer material layers in the thin film structure include one polymer selected from the group consisting of poly(methyl methacrylate), poly(ethyl methacrylate), and UV curable resins.

5. (Original) The organic light-emitting device of claim 4, wherein the polymer material layers in the thin film structure are in the range of about 50 to 1000 nm in thickness.

6. (Original) The organic light-emitting device of claim 1, wherein the ceramic material layers in the thin film structure include one material selected from the group consisting of nitrides, oxides, and nitrogen oxides.

7. (Original) The organic light-emitting device of claim 6, wherein the ceramic material layers in the thin film structure are in the range of about 10 to 1000 nm in thickness.

8. (Original) The organic light-emitting device of claim 6, wherein the ceramic material layers in the thin film structure include one material selected from the group consisting of silicon nitride, aluminum nitride, titanium nitride, silicon oxide, aluminum oxide, titanium oxide, silicon nitrogen oxide, aluminum nitrogen oxide and titanium nitrogen oxide.

9. (Original) The organic light-emitting device of claim 1, wherein the thick organic insulation layer in the encapsulation layer includes UV curable resins.

10. (Original) The organic light-emitting device of claim 9, wherein the thick organic insulation layer in the encapsulation layer is in the range of about 10 to 1000 μm in thickness.

11-22 (Canceled)

23. (New) The organic light-emitting device of claim 4, selected from poly(methyl methacrylate), poly(ethyl methacrylate) and UV curable resins.

24. (New) An encapsulation layer comprising:

a thin multilayer structure which has a period number of alternating layers formed of a polymer material layer and a ceramic material layer;

the encapsulation layer also includes a thick organic insulation layer on top of the thin multilayer structure, which is made up of polymer material.

25. (New) The encapsulation layer of claim 24, wherein the period number of the thin multilayer structure is an integer of 1 to 10.

26. (New) The encapsulation layer of claim 24, wherein the polymer material layers in the thin film structure are made up of one kind of polymer selected from poly(methyl methacrylate), poly(ethyl methacrylate) and UV curable resins.

27. (New) The encapsulation layer of claim 26, wherein the polymer material layers in the thin film structure are in the range of about 50 to 1000 nm in thickness.

28. (New) The encapsulation layer of claim 24, wherein the ceramic material layers in the thin film structure are made up of one material selected from nitride, oxide and nitrogen oxide.

29. (New) The encapsulation layer of claim 28, wherein the ceramic material layers

in the thin film structure are in the range of about 10 to 1000 nm in thickness.

30. (New) The encapsulation layer of claim 28, wherein the ceramic material layers in the thin film structure are made up of one material selected from silicon nitride, aluminum nitride, titanium nitride, silicon oxide, aluminum oxide, titanium oxide, silicon nitrogen oxide, aluminum nitrogen oxide and titanium nitrogen oxide.

31. (New) The encapsulation layer of claim 24, wherein the thick organic insulation layer in the encapsulation layer is made up of UV curable resins.

32. (New) The encapsulation layer of claim 31, wherein the thick organic insulation layer in the encapsulation layer is in the range of about 10 to 1000 μm in thickness.